

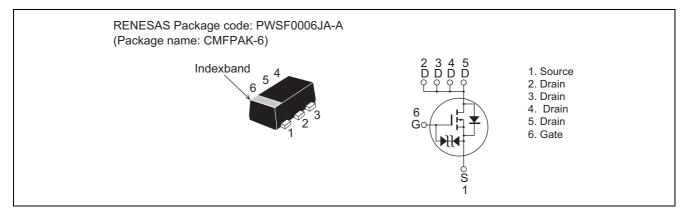
HAT1108C Silicon P Channel MOS FET Power Switching

REJ03G1234-0400 Rev.4.00 Jun. 13, 2005

Features

- Low on-resistance $R_{DS(on)} = 155 \text{ m}\Omega \text{ typ.} (at V_{GS} = -10 \text{ V})$
- Low drive current.
- 4.5 V gate drive devices.
- High density mounting

Outline



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Ratings	Unit
Drain to Source voltage	V _{DSS}	-30	V
Gate to Source voltage	V _{GSS}	+20/ -10	V
Drain current	ID	-1.5	A
Drain peak current	I _D (pulse) ^{Note1}	-6	A
Body - Drain diode reverse drain current	I _{DR}	-1.5	A
Channel dissipation	Pch ^{Note 2}	830	mW
Channel temperature	Tch	150	٥C
Storage temperature	Tstg	-55 to +150	°C

Notes 1. $PW \le 10 \ \mu s$, duty cycle $\le 1\%$

2. When using the glass epoxy board. (FR4 40 \times 40 \times 1.6mm), Ta = 25 $^{\circ}\text{C}$



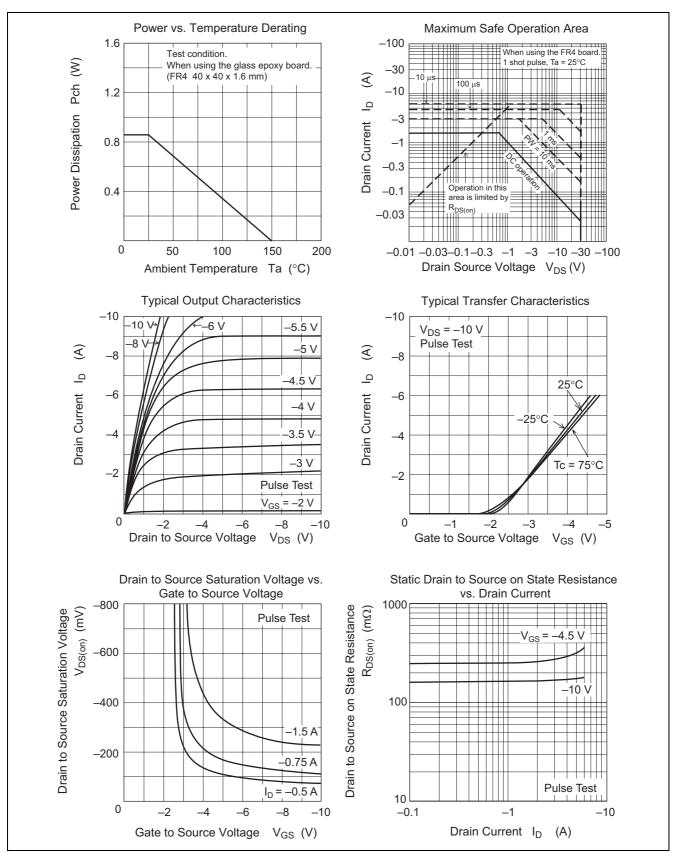
Electrical Characteristics

			1			$(Ta = 25^{\circ}C)$	
Item	Symbol	Min.	Тур.	Max.	Unit	Test Conditions	
Drain to Source breakdown voltage	V _{(BR)DSS}	-30		—	V	$I_D = -10 \text{ mA}, V_{GS} = 0$	
Gate to Source breakdown voltage	V _{(BR)GSS}	-20	_	_	V	$I_{G} = \pm 100 \ \mu A, \ V_{DS} = 0$	
		+10					
Gate to Source leakage current	I _{GSS}	—	—	±10	μA	$V_{GS} = -16/ + 8 V, V_{DS} = 0$	
Drain to Source leakage current	I _{DSS}	—	—	-1	μA	$V_{DS} = -30 V, V_{GS} = 0$	
Gate to Source cutoff voltage	V _{GS(th)}	-0.5	—	-2.0	V	$I_D = -1 \text{ mA}, V_{DS} = -10 \text{ V}^{Note4}$	
Drain to Source on state resistance	R _{DS(on)}	—	155	194	mΩ	$I_D = -0.75A, V_{GS} = -10 V^{Note4}$	
		—	245	356	mΩ	$I_D = -0.75A, V_{GS} = -4.5 V^{Note4}$	
Forward transfer admittance	y _{fs}	0.65	1		s	$I_D = -0.75A, V_{DS} = -10 V^{Note4}$	
Input capacitance	Ciss	—	160	-	pF	$V_{DS} = -10 V, V_{GS} = 0,$	
Output capacitance	Coss	—	50		pF	f = 1 MHz	
Reverse transfer capacitance	Crss	—	30		pF		
Total gate charge	Qg	_	3		nC	$V_{DS} = -10 \text{ V}, V_{GS} = -10 \text{ V},$ $I_D =1.5 \text{ A}$	
Gate to Source charge	Qgs	_	0.2		nC		
Gate to Drain charge	Qgd	_	0.6		nC		
Turn - on delay time	t _{d(on)}	_	20	_	ns	$ \begin{array}{l} V_{DS} = -10 \ V, \ V_{GS} = -10 \ V, \\ I_D = -0.75 \ A, \ R_L = 13.3 \ \Omega, \\ R_g = 4.7 \ \Omega \end{array} $	
Rise time	tr	_	13	_	ns		
Turn - off delay time	t _{d(off)}	_	28	—	ns		
Fall time	t _f	_	5	—	ns	1	
Body - Drain diode forward voltage	V _{DF}		-0.85	-1.2	V	$I_F = -1.5 \text{ A}, V_{GS} = 0$	

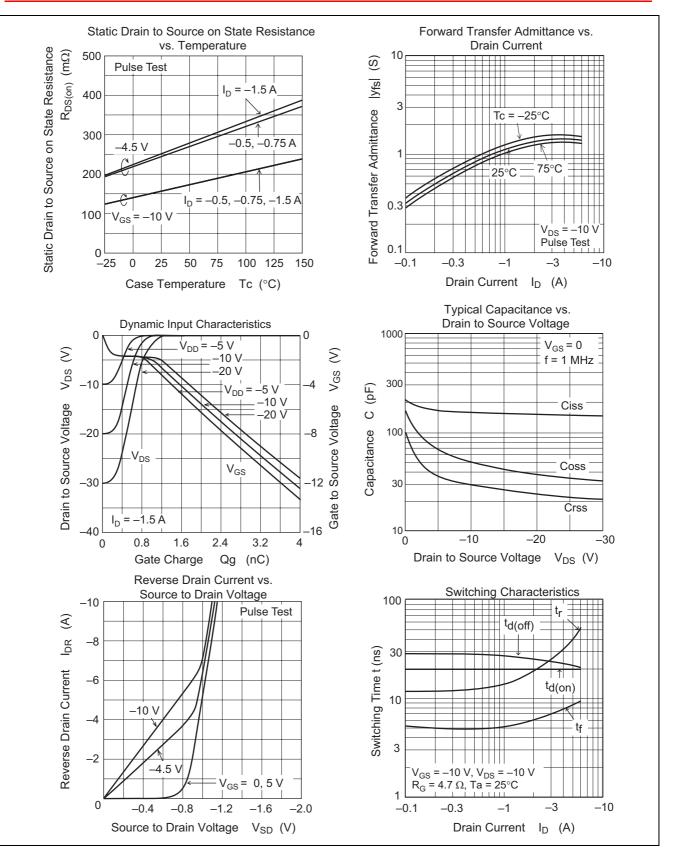
Notes: 4. Pulse test



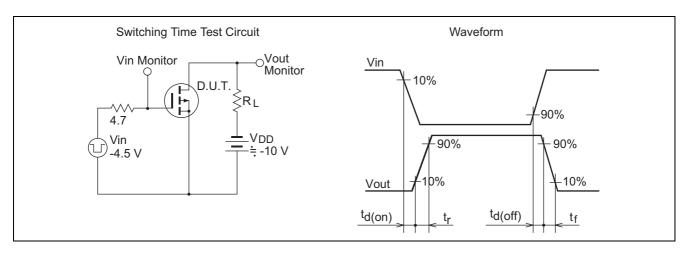
Main Characteristics





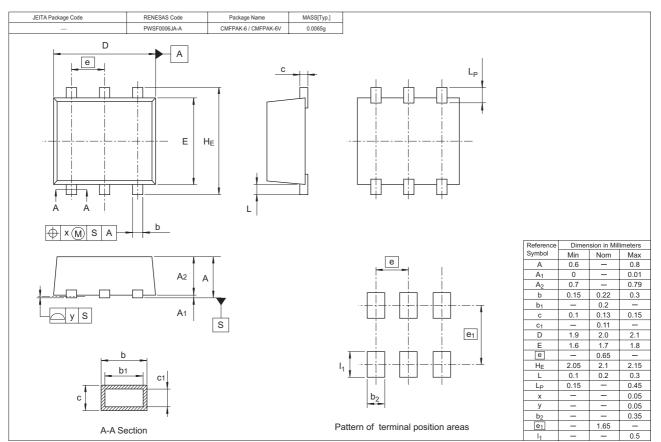








Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
HAT1108C-EL-E	3000 pcs	Taping

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.



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